



SOT1903-1

plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body

25 May 2018

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HX2QFN24
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-12-2016
Manufacturer package code	SOT1903-1

Table 1. Package summary

Parameter		Min	Nom	Max	Unit
package length		2.35	2.4	2.45	mm
package width		3.15	3.2	3.25	mm
seated height		0.3	0.35	0.4	mm
nominal pitch		-	0.4	-	mm
actual quantity of termination		-	24	-	A/A



plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body

2. Package outline

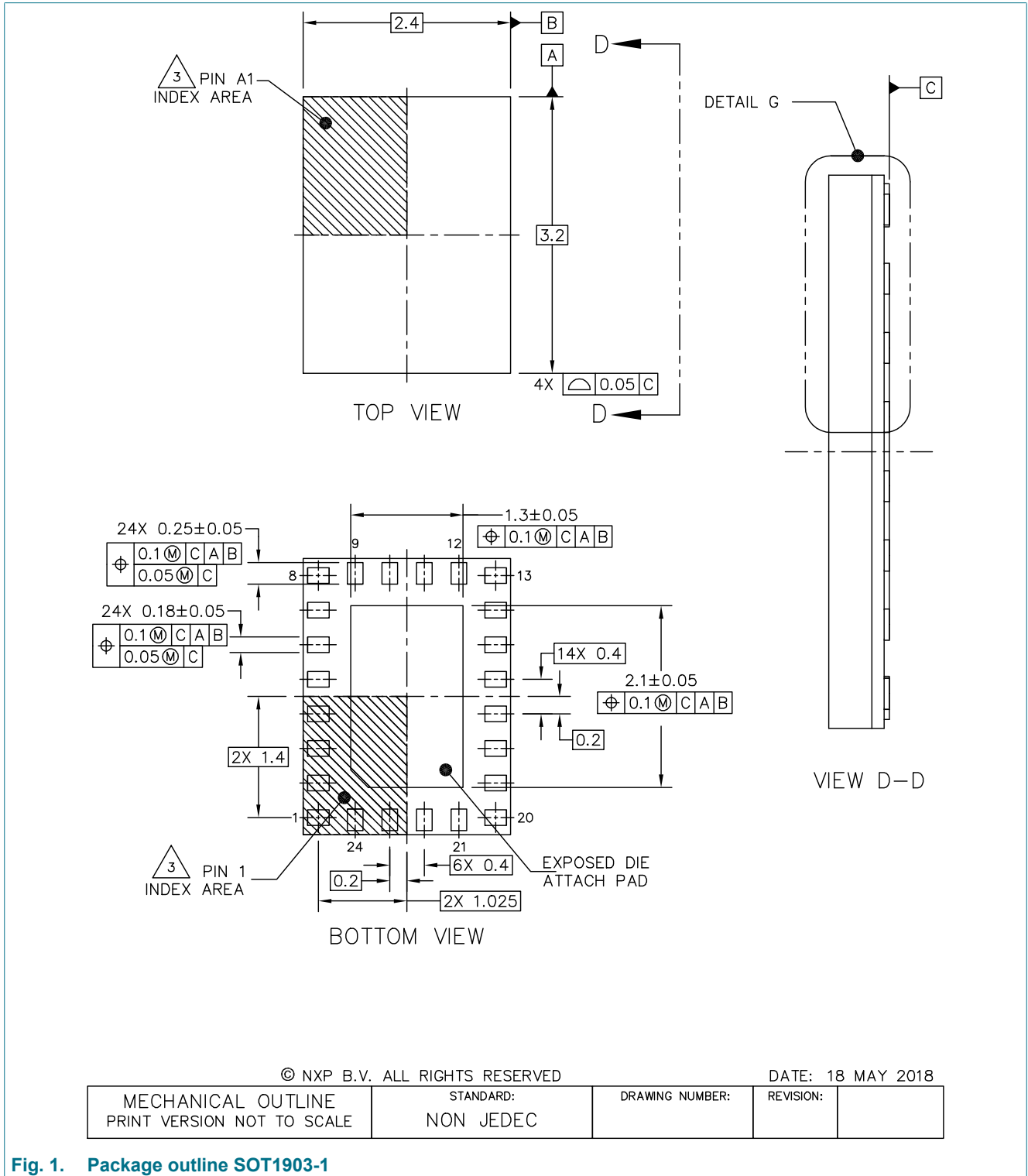
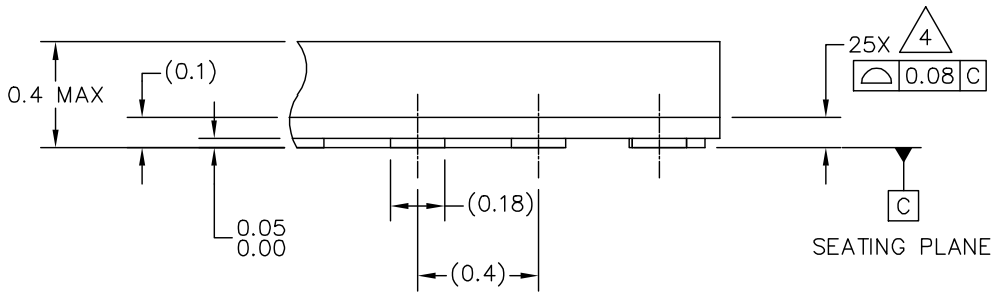


Fig. 1. Package outline SOT1903-1

plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body



DETAIL G
VIEW ROTATED 90° CW

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Fig. 2. Package outline detail G of HX2QFN24 (SOT1903-1)

plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.

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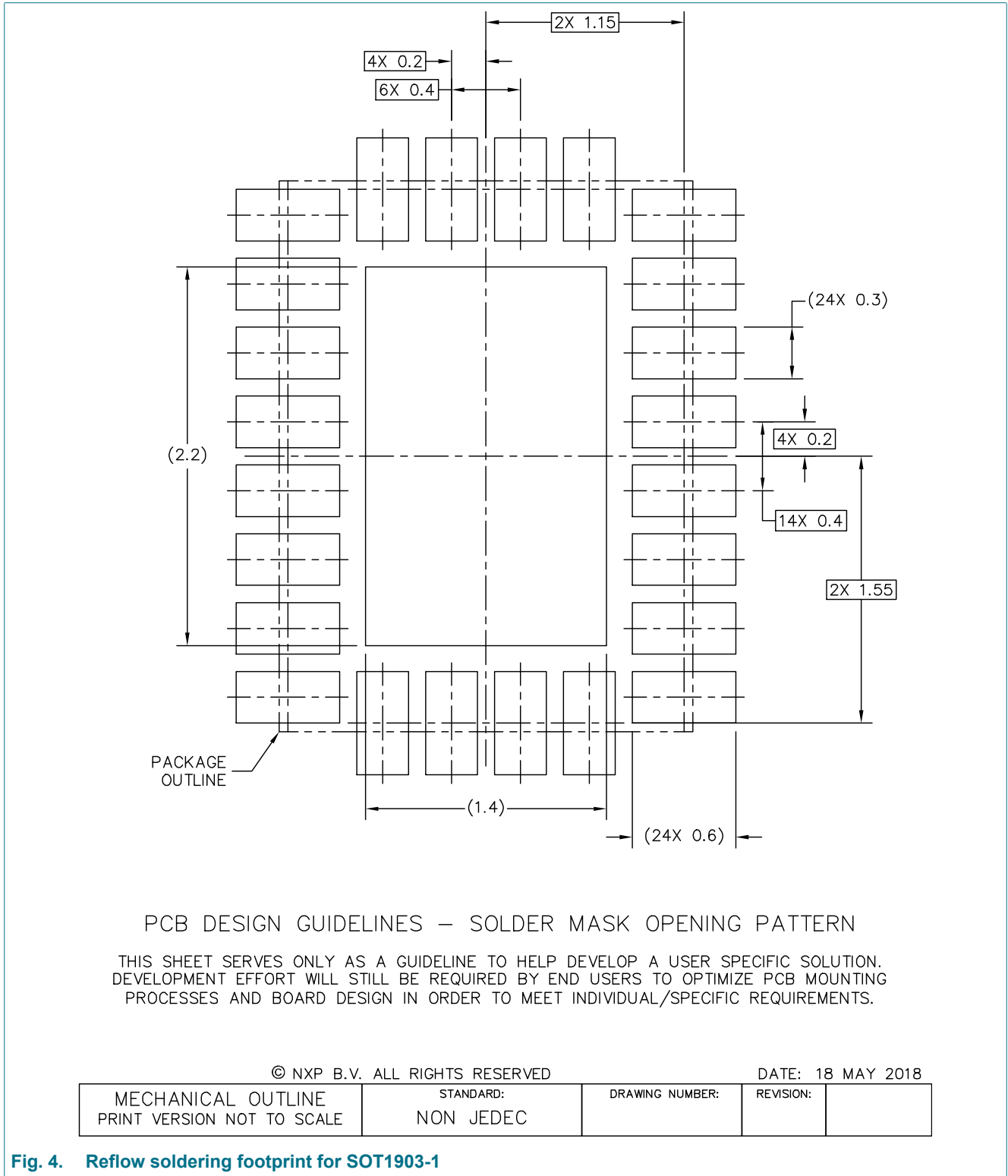
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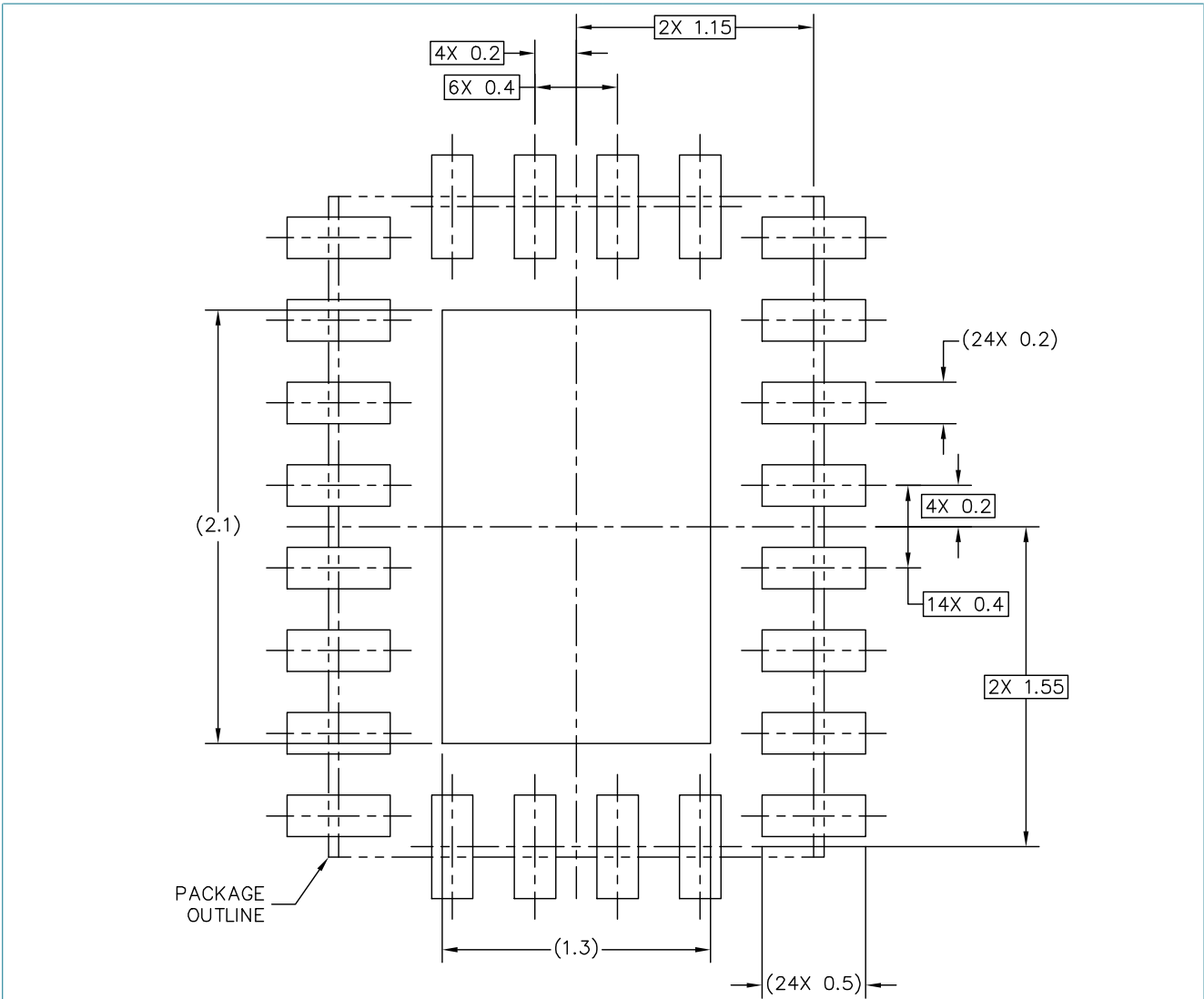
Fig. 3. Package outline note HX2QFN24 (SOT1903-1)

plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body

3. Soldering



plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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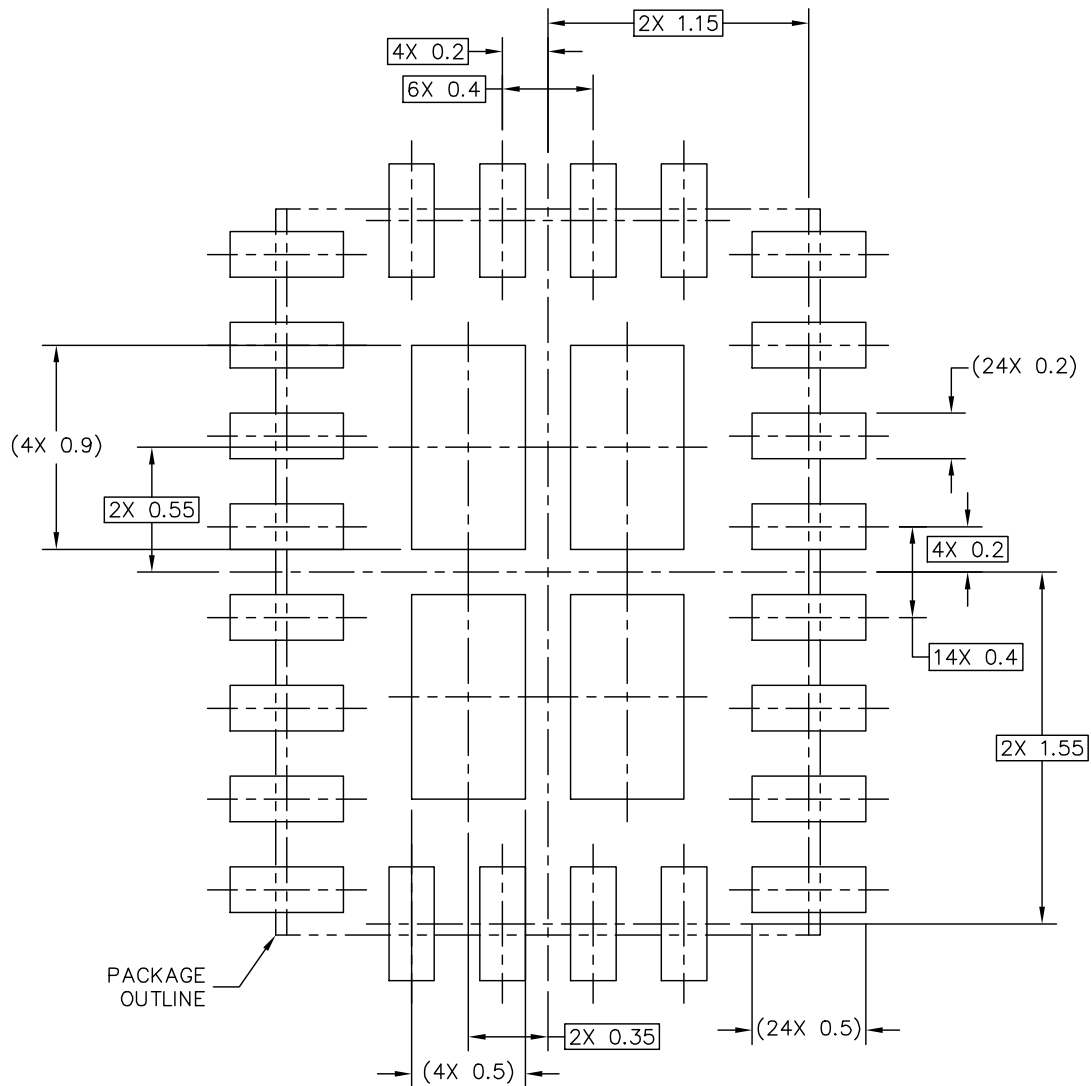
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Fig. 5. Reflow soldering footprint part2 for HX2QFN24 (SOT1903-1)

plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body



RECOMMENDED STENCIL THICKNESS 0.1

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Fig. 6. Reflow soldering footprint part3 for HX2QFN24 (SOT1903-1)

plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body

4. Legal information

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plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 0.4 mm pitch, 2.4 mm x 3.2 mm x 0.35 mm body

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